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**PATENT APPLICATION**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re application of

Docket No: Q65445

Hiroshi SUMI, et al.

Appln. No.: 09/904,097

Group Art Unit: 2827

Confirmation No.: 1333

Examiner: Jose H. Alcala

Filed: July 13, 2001

For: PASTE FOR FILLING THROUGH HOLE AND PRINTED WIRING BOARD USING  
SAME

**AMENDMENT UNDER 37 C.F.R. § 1.111**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

This Amendment is submitted in response to the Office Action dated January 2, 2003.

Please amend the above-identified application as follows:

**IN THE SPECIFICATION:**

**Please replace the paragraph on page 7 at lines 4-11:**

In these drawings, 1 designates a core substrate, 2 a substrate, 3 an inside (wall) surface of a hole, 4 a conductor layer, 5 a roughed surface, 6 a hydrophobic surface, 7 a conductor layer surface, 8 a water droplet, 80 contact point of water droplet with the surface of a conductor layer surface, 81 the top of a water droplet, 82 a hypothetical line, 83 a horizontal line, 9 an angle ( $\theta$ ), 10 a cured throughhole-filling material, 11 a dent (d), and 12 a gap.